

L7 ANSWER 1 OF 1 WPIX COPYRIGHT 2003 THOMSON DERWENT on STN  
 ACCESSION NUMBER: 1997-149843 [14] WPIX  
 DOC. NO. NON-CPI: N1997-123776  
 DOC. NO. CPI: C1997-048043  
 TITLE: Prepreg - contains base sheet impregnated with epoxy resin compsn. contg. brominated epoxy resin, styrene and maleic anhydride copolymer as curing agent, styrene cpd. and solvent.  
 DERWENT CLASS: A13 A21 P73 V04  
 PATENT ASSIGNEE(S): (MITN) MITSUBISHI GAS CHEM CO INC  
 COUNTRY COUNT: 1  
 PATENT INFORMATION:

PATENT NO	KIND	DATE	WEEK	LA	PG	MAIN IPC
JP--09025349	A	19970128	(199714)*		7	C08J-005-24<--

## APPLICATION DETAILS:

PATENT NO	KIND	APPLICATION	DATE
JP--09025349	A	1995JP-0174975	19950711

PRIORITY APPLN. INFO: 1995JP-0174975 19950711

INT. PATENT CLASSIF.:

MAIN: C08J-005-24

SECONDARY: B32B-027-04; C09K-021-14; H05K-001-03

## BASIC ABSTRACT:

JP 09025349 A UPAB: 19970407

The prepreg is prepnd. by impregnating a base sheet with an epoxy resin compsn. comprising as essential components, (I) epoxy resin consisting of at least 1 epoxy resin having more than 2 epoxy gps. in mol., where at least 1 among them is brominated epoxy resin; (II) curing agent for epoxy resin, which is a copolymer prepnd. from styrene and maleic anhydride as essential component; (III) styrene-type cpd. consisting of low mol. wt. polymer of styrene or subst. styrene and/or styrene-addn.-type phenols; and (IV) solvent dissolving these components (I)-(III).

Also claimed is a laminated board prepnd. by laminating the prepreg and the moulding.

USE - The laminated board is used for electric insulating material.

ADVANTAGE - The laminated board has low dielectric constant, low dielectric loss tangent and high resistance against heat.

Dwg. 0/0

FILE SEGMENT: CPI EPI GMPI

FIELD AVAILABILITY: AB

MANUAL CODES: CPI: A04-C04; A04-F05; A05-A01B1; A08-D02; A12-S08A

EPI: V04-R07L; V04-R07P